CATHODE (−) END VIEW

SIDE VIEW

ANODE (+) END VIEW

BOTTOM VIEW

Termination cutout
at KEMET's option,
either end

Click here for the 3D model.

General Information

Series	T489
Dielectric	MnO2 Tantalum
Style	SMD Chip
Description	SMD, MnO2, Molded, Low Leakage
Features	Low Leakage
RoHS	Yes
Termination	Tin
AEC-Q200	No
Component Weight	446.84 mg
Shelf Life	156 Weeks
MSL	1

Dimensions

Footprint	7343
L	7.3mm +/-0.3mm
W	4.3mm +/-0.3mm
H	2.8mm +/-0.3mm
T	0.13mm REF
S	1.3mm +/-0.3mm
F	2.4mm +/-0.1mm
A	3.8mm MIN
B	0.5mm +/-0.15mm
E	3.5mm REF
G	3.5mm REF
P	0.9mm REF
R	1mm REF
X	0.1mm +/-0.1mm

Specifications

Capacitance	15 uF
Capacitance Tolerance	20%
Voltage DC	20 VDC (85C), 13.4 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	6% 120Hz 25C
Failure Rate	N/A
Resistance	1100 mOhms (100kHz 25C)
Ripple Current	369 mA (rms, 100kHz 25C)
Leakage Current	2.3 uA (5min 25°C)

Packaging Specifications

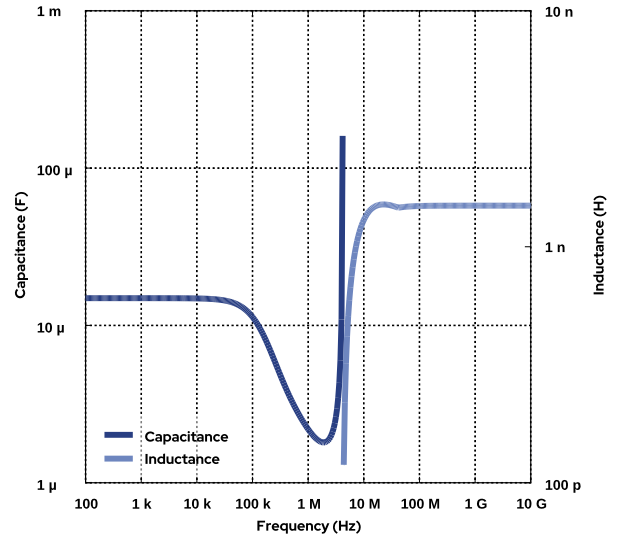|	
Packaging	T&R, 178mm
Packaging Quantity	500

Simulations

For the complete simulation environment please visit K-SIM.

Impedance and ESR
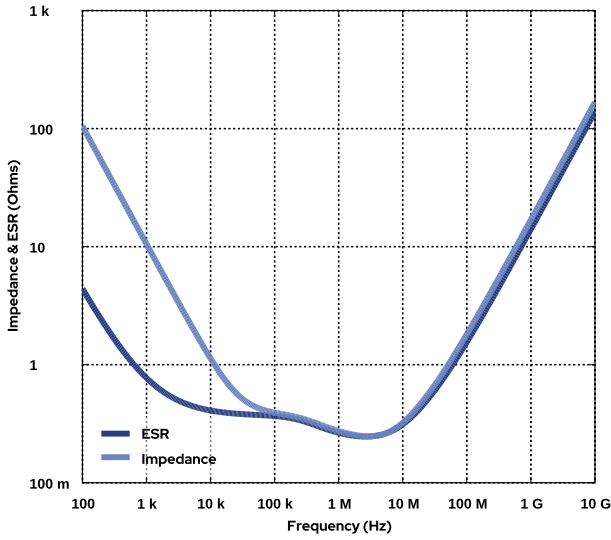
Capacitance and Inductance

Current and Voltage

S11

S21

S21 Magnitude
S21 Phase

Magnitude (db)
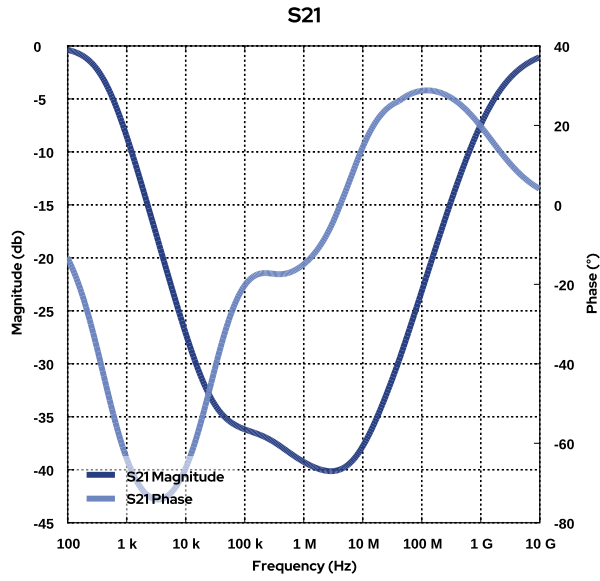Phase (°)
Frequency (Hz)
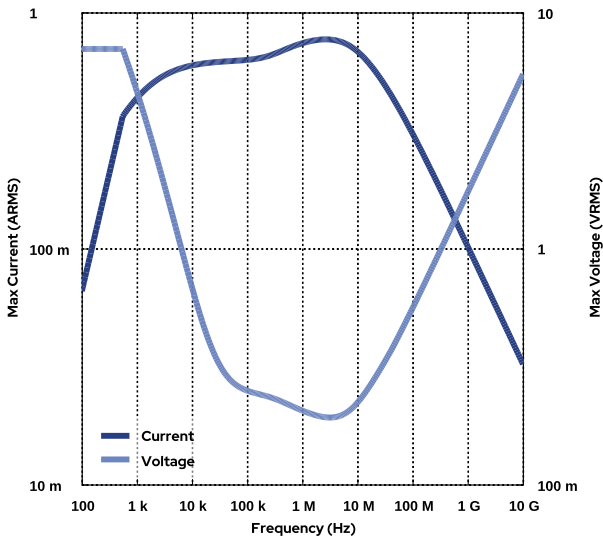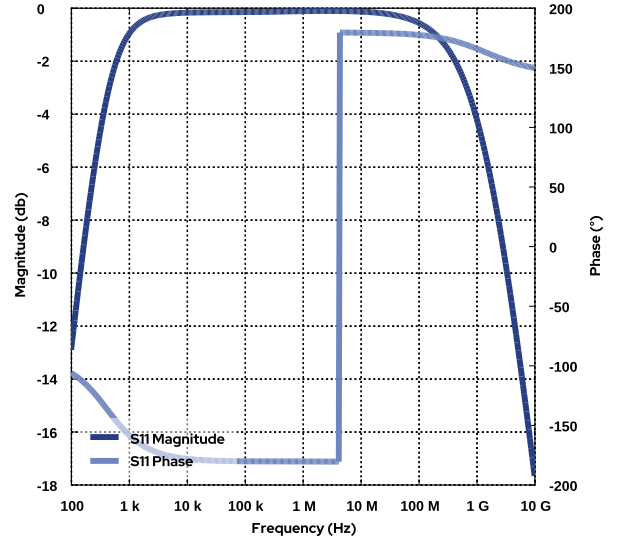
These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.
- The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
- The effects shown herein are based on measured data from a multiple part sample of the parts in question.
- Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
- The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages generated at any other harmonics.
- Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

If you have any questions please contact K-SIM.